

ABSTRACT

A multilayer printed wiring board (PWB) including via holes with satisfactory quality without defective shapes like swelling or recession on the end faces is provided. The multilayer PWB includes a build-up board of plural insulation layers as the main structure. In each of the insulation layers, via holes (columnar conductors) for electrically connecting between conductor circuits on the base layer or adjacent layers are formed. The via holes are formed by patterning metal foil with conductivity. The height "H" of the via holes (dimension in the thickness direction of the via hole forming layer) depends on the thickness "D" of the original metal foil only. Accordingly, the via holes can be formed without carrying out filling with conductive paste or electrolytic plating. Thus, multilayer PWB having via holes with satisfactory quality without defective shapes like swelling or recession on the end faces can be manufactured.